

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SANG MOO LEE	10/17/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEOUL LASER DIEBOARD SYSTEM CO. LTD.
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<b>City:</b>	SAN DIEGO
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	92131
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15094867
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	113764-023UT1
<b>NAME OF SUBMITTER:</b>	JENNIFER RIEWALD
<b>SIGNATURE:</b>	/Jennifer Riewald/
<b>DATE SIGNED:</b>	01/06/2017
<b>Total Attachments: 1</b>	
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**ASSIGNMENT**

WHEREAS, I, as a below named inventor, am a sole inventor of certain new and useful improvements in **CHANNEL BENDER** (Application Number: 15/094,867, Filing Date: April 8, 2016).

AND WHEREAS, Seoul Laser Dieboard System Co., Ltd., a limited partnership, with offices at 10035 Carroll Canyon Boulevard, Suite B, San Diego, CA 92131 (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefore in the United States and in any and all foreign countries;

NOW THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, their successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any prior applications and any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or their designee(s), as ASSIGNEE or their successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at their own expense;

And I further agree that ASSIGNEE will, upon their request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

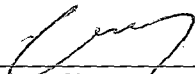
This assignment executed on the dates indicated below.

Sang Moo Lee

Name of first inventor

INCHON, KOREA

Residence of first inventor



Signature of first inventor

10/17, 2016

Date of Assignment